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ANALOG DEVICES

High-Speed 8-Bit Monolithic A/D Converter

AD9002

FEATURES

150 MSPS Encode Rate Low Input Capacitance: 17 pF Low Power: 750 mW -5.2 V Single Supply MIL-STD-883 Compliant Versions Available

APPLICATIONS

Radar Systems Digital Oscilloscopes/ATE Equipment Laser/Radar Warning Receivers Digital Radio Electronic Warfare (ECM, ECCM, ESM) Communication/Signal Intelligence

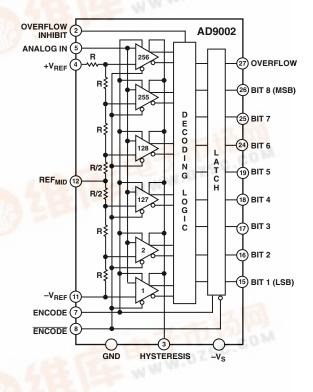
GENERAL DESCRIPTION

The AD9002 is an 8-bit, high-speed, analog-to-digital converter. The AD9002 is fabricated in an advanced bipolar process that allows operation at sampling rates in excess of 150 megasamples/ second. Functionally, the AD9002 is comprised of 256 parallel comparator stages whose outputs are decoded to drive the ECL compatible output latches.

An exceptionally wide large signal analog input bandwidth of 160 MHz is due to an innovative comparator design and very close attention to device layout considerations. The wide input bandwidth of the AD9002 allows very accurate acquisition of high speed pulse inputs, without an external track-and-hold. The comparator output decoding scheme minimizes false codes, which is critical to high speed linearity.

The AD9002 provides an external hysteresis control pin that can be used to optimize comparator sensitivity to further improve performance. Additionally, the AD9002's low power dissipation of 750 mW makes it usable over the full extended temperature range. The AD9002 also incorporates an overflow bit to indicate overrange inputs. This overflow output can be disabled with the overflow inhibit pin.

FUNCTIONAL BLOCK DIAGRAM



The AD9002 is available in two grades, one with 0.5 LSB linearity and one with 0.75 LSB linearity. Both versions are offered in an industrial grade, -25°C to +85°C, packaged in a 28-lead DIP and a 28-leaded JLCC. The military temperature range devices, -55°C to +125°C, are available in ceramic DIP and LCC packages and comply with MIL-STD-883 Class B.

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REV.

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AD9002-SPECIFICATIONS **ELECTRICAL CHARACTERISTICS** ($-V_s = -5.2$ V; Differential Reference Voltage = 2.0 V; unless otherwise noted)

			000240			000300			000261	NEE		0000TT	VTE	
Parameter	Temp	AD Min	9002AD Typ	Max Max	AD Min	9002BD Typ	Max	AL Min	09002SI Typ	Max	Al Min)9002TI Тур	Max	Unit
RESOLUTION		8			8			8			8			Bits
DC ACCURACY Differential Linearity Integral Linearity No Missing Codes	25°C Full 25°C Full Full	GU	0.6 0.6 JARANT	0.75 1.0 1.0 1.2 TEED	GU	0.4 0.4 ARANT	0.5 0.75 0.5 1.2 TEED	GU	0.6 0.6 ARANT	0.75 1.0 1.0 1.2 TEED	GU	0.4 0.4 VARANT	0.5 0.75 0.5 1.2 TEED	LSB LSB LSB LSB
INITIAL OFFSET ERROR Top of Reference Ladder Bottom of Reference Ladder Offset Drift Coefficient	25°C Full 25°C Full Full		8 4 20	14 17 10 12		8 4 20	14 17 10 12		8 4 20	14 17 10 12		8 4 20	14 17 10 12	$\begin{array}{c} mV\\ mV\\ mV\\ mV\\ \mu V/^{\circ}C \end{array}$
ANALOG INPUT Input Bias Current ¹ Input Resistance Input Capacitance Large Signal Bandwidth ² Input Slew Rate ³	25°C Full 25°C 25°C 25°C 25°C	25	60 200 17 160 440	200 200 22	25	60 200 17 160 440	200 200 22	25	60 200 17 160 440	200 200 22	25	60 200 17 160 440	200 200 22	μΑ μΑ kΩ pF MHz V/μs
REFERENCE INPUT Reference Ladder Resistance Ladder Temperature Coefficient Reference Input Bandwidth	25°C 25°C	40	80 0.25 10	110	40	80 0.25 10	110	40	80 0.25 10	110	40	80 0.25 10	110	Ω Ω/°C MHz
DYNAMIC PERFORMANCE Conversion Rate Aperture Delay Aperture Uncertainty (Jitter) Output Delay (t _{PD}) ^{4,5} Transient Response ⁶ Overvoltage Recovery Time ⁷ Output Rise Time ⁴ Output Fall Time ⁴ Output Time Skew ^{4,8}	25°C 25°C 25°C 25°C 25°C 25°C 25°C 25°C	125 2.5	150 1.3 15 3.7 6 6 0.6	5.5 3.0 2.5	125 2.5	150 1.3 15 3.7 6 6 0.6	5.5 3.0 2.5	125 2.5	150 1.3 15 3.7 6 6	5.5 3.0 2.5	125 2.5	150 1.3 15 3.7 6 6 0.6	5.5 3.0 2.5	MSPS ns ps ns ns ns ns ns ns ns
ENCODE INPUT Logic "1" Voltage ⁴ Logic "0" Voltage ⁴ Logic "1" Current Logic "0" Current Input Capacitance Encode Pulsewidth (Low) ⁹ Encode Pulsewidth (High) ⁹	Full Full Full 25°C 25°C 25°C	-1.1 1.5 1.5	3	-1.5 150 120	-1.1 1.5 1.5	3	-1.5 150 120	-1.1 1.5 1.5	3	-1.5 150 120	-1.1 1.5 1.5	3	-1.5 150 120	V V μA μA pF ns ns
OVERFLOW INHIBIT INPUT 0 V Input Current	Full		144	300		144	300		144	300		144	300	μΑ
AC LINEARITY ¹⁰ Effective Bits ¹¹ In-Band Harmonics dc to 1.23 MHz dc to 9.3 MHz dc to 19.3 MHz Signal-to-Noise Ratio ¹²	25°C 25°C 25°C 25°C 25°C	48 46	7.6 55 50 44 47.6		48 46	7.6 55 50 44 47.6		48 46	7.6 55 50 44 47.6		48 46	7.6 55 50 44 47.6		Bits dB dB dB dB
Two Tone Intermod Rejection ¹³ DIGITAL OUTPUTS ⁴ Logic "1" Voltage Logic "0" Voltage	25°C Full Full	-1.1	60	-1.5	-1.1	60	-1.5	-1.1	60	-1.5	-1.1	60	-1.5	dB V V
POWER SUPPLY ¹⁴ Supply Current (-5.2 V) Nominal Power Dissipation Reference Ladder Dissipation Power Supply Rejection Ratio ¹⁵	25°C Full 25°C 25°C 25°C		145 750 50 0.8	175 200 1.5		145 750 50 0.8	175 200 1.5	skow diffe	145 750 50 0.8	175 200 1.5		145 750 50 0.8	175 200 1.5	mA mA mW mW mV/V

NOTES ¹Measured with AIN = 0 V. ²Measured by FFT analysis where fundamental is -3 dBc. ³Input slew rate derived from rise time (10 to 90%) of full scale input. ⁴Outputs terminated through 100 Ω to -2 V. ⁵Measured from ENCODE in to data out for LSB only. ⁶Eas full scale stars input 8 bit scauseous is attained in accelerated time.

⁶For full-scale step input, 8-bit accuracy is attained in specified time. ⁷Recovers to 8-bit accuracy in specified time after 150% full-scale input overvoltage.

bit-to-bit time skew differences. ⁹ENCODE signal rise/fall times should be less than 10 ns for normal operation.

¹⁰Measured at 125 MSPS encode rate.
¹¹Analog input frequency = 1.23 MHz.
¹²RMS signal to rms noise, with 1.23 MHz analog input signal.
¹³Input signals 1 V p-p @ 1.23 MHz and 1 V p-p @ 2.30 MHz.
¹⁴Supplies should remain stable within ±5% for normal operation.

¹⁵Measured at $-5.2 \text{ V} \pm 5\%$.

ABSOLUTE MAXIMUM RATINGS¹

Supply Voltage $(-V_S)$
Analog-to-Digital Supply Voltage Differential 0.5 V
Analog Input Voltage
Digital Input Voltage
Reference Input Voltage $(+V_{REF} - V_{REF})^2 \dots -3.5$ V to $+0.1$ V
Differential Reference Voltage 2.1 V
Reference Midpoint Current ±4 mA
ENCODE to ENCODE Differential Voltage
Digital Output Current 20 mA
Operating Temperature Range
AD9002AD/BD/AJ/BJ25°C to +85°C
AD9002SE/SD/TD/TE
Storage Temperature Range
Junction Temperature ³ 150°C
Lead Soldering Temperature (10 sec) 300°C

NOTES

¹Absolute maximum ratings are limiting values, to be applied individually, and beyond which the serviceability of the circuit may be impaired. Functional operability under any of these conditions is not necessarily implied. Exposure to absolute maximum rating conditions for extended periods of time may affect device reliability.

 $^{2}+V_{REF} \ge -V_{REF}$ under all circumstances.

³Maximum junction temperature (t₁ max) should not exceed 175°C for ceramic packages, and 150°C for plastic packages:

 $t_{J} = PD (\theta_{JA}) + t_{A}$ $PD (\theta_{JC}) + t_{C}$

where PD = power dissipation

- θ_{JA} = thermal impedance from junction to ambient (°C/W)
- $\theta_{\rm JC}$ = thermal impedance from junction to case (°C/W)

 $\dot{t_A}$ = ambient temperature (°C)

 $t_{\rm C}$ = case temperature (°C)

Typical thermal impedances are:

Ceramic DIP $\theta_{JA} = 56^{\circ}$ C/W; $\theta_{JC} = 20^{\circ}$ C/W Ceramic LCC $\theta_{JA} = 69^{\circ}$ C/W; $\theta_{JC} = 23^{\circ}$ C/W PLCC $\theta_{IA} = 60^{\circ}C/W$; $\theta_{IC} = 19^{\circ}C/W$.

Recommended	Operating	Conditions
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	Input Voltage						
Parameter	Min	Nominal	Max				
-V _S	-5.46	-5.20	-4.94				
+V _{REF}	-V _{REF}	0.0 V	+0.1				
-V _{REF}	-2.1	-2.0	+V _{REF}				
Analog Input	-V _{REF}		$+V_{REF}$				

EXPLANATION OF TEST LEVELS

Test Level I	_	100% production tested.
Test Level II	_	100% production tested at 25°C, and sample
		tested at specified temperatures.
Test Level III	_	Sample tested only.
Test Level IV	_	Parameter is guaranteed by design and
		characterization testing.
Test Level V	_	Parameter is a typical value only.
Test Level VI	_	All devices are 100% production tested at

25°C. 100% production tested at temperature extremes for extended temperature devices; sample tested at temperature extremes for commercial/industrial devices.

ORDERING GUIDE

Model	Linearity	Temperature Range	Package Option*
AD9002AD	0.75 LSB	–25°C to +85°C	D-28
AD9002BD	0.50 LSB	–25°C to +85°C	D-28
AD9002AJ	0.75 LSB	–25°C to +85°C	J-28
AD9002BJ	0.50 LSB	–25°C to +85°C	J-28
AD9002SD/883B	0.75 LSB	–55°C to +125°C	D-28
AD9002SE/883B	0.75 LSB	–55°C to +125°C	E-28A
AD9002TD/883B	0.50 LSB	–55°C to +125°C	D-28
AD9002TE/883B	0.50 LSB	–55°C to +125°C	E-28A

*D = Ceramic DIP; E = Leadless Ceramic Chip Carrier; J = Ceramic Chip Carrier, J-Formed Leads.

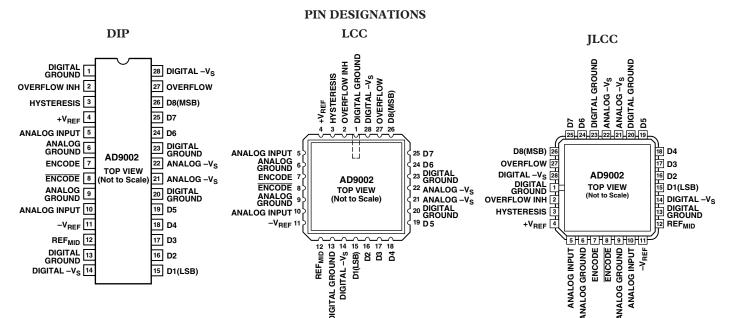
CAUTION_

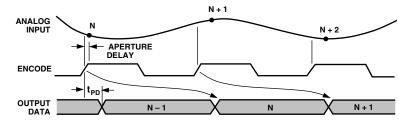
ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the AD9002 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high-energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



FUNCTIONAL DESCRIPTION

Pin #	Mnemonic	Description								
1 2	DIGITAL GROUND OVERFLOW INH	One of four digital ground pins. All digital ground pins should be connected together. OVERFLOW INHIBIT controls the data output polarity for overvoltage inputs.								
		Analog Input	Overflow Enabled (Floating or -5.2 V) of D1-D8		erflov D1–D		ibited	(G]	ND)	
		$V_{IN} > +V_{REF}$	1 0 0 0 0 0 0 0 0) 0	1 1	1 1	1 1	1	1	1
		$V_{IN} \leq +V_{REF}$	0 X X X X X X X X	X 0 2	x x 2	хх	хх	Х	Х	1
3	HYSTERESIS +V _{REF}	from -5.2 V to -2.2 V The most positive refe	l voltage varies the comparato at the Hysteresis control pin. rence voltage for the internal	Normally resistor la	conve dder.	rted t	o –5.2 '	V.	, for a	change
5 6	ANALOG INPUT ANALOG GROUND		ut pins. Both analog input pir und pins. Both analog ground						er	
7	ENCODE	Noninverted input of	the differential encode input. ' ched on the rising edge of the	This pin is	s driver	n in c				
8	ENCODE	Inverted input of the c	lifferential encode input. This	s pin is dri	ven in	conju				ODE.
9	ANALOG GROUND	One of two analog ground pins. Both analog ground pins should be connected together.								
10	ANALOG INPUT		One of two analog input pins. Both analog inputs should be connected together. The most negative reference voltage for the internal resistor ladder.							
11	-V _{REF}			resistor la	idder.					
12	REF _{MID} DIGITAL GROUND		he internal resistor ladder. ound pins. All digital ground p		1 1			<u>.</u> 1		
13 14	DIGITAL GROUND DIGITAL –V _S		igital supply pins (nominally -							be con-
15	D1 (LSB)	Digital Data Output								
16-19	D2-D5	Digital Data Output								
20	DIGITAL GROUND		ound pins. All digital ground p	oins should	l be co	nnect	ed toge	ther		
21, 22	ANALOG –V _S		nalog supply pins (nominally -							l be con-
23	DIGITAL GROUND		und pins. All digital ground p	oins should	l be co	nnect	ed toge	ther		
24, 25	D6, D7	Digital Data Output					0			
26	D8 (MSB)	Digital Data Output								
27	OVERFLOW	INHIBIT is enabled (Logic high indicates an input overflow enabled, -5.2 V). See	e OVERF	LOWI	NHI	BIT.			
28	DIGITAL –V _S	One of two negative connected together.	digital supply pins (nominal	ly –5.2 V)	. Both	digit	al supp	oly p	oins sh	iould be







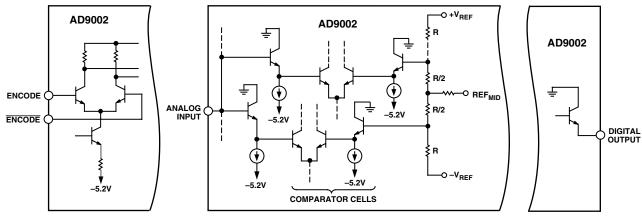
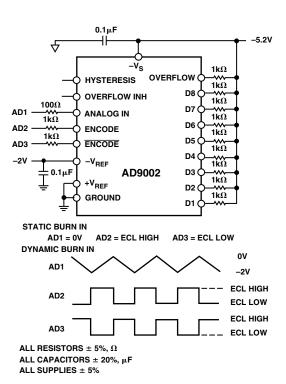


Figure 2. Input/Output Circuits





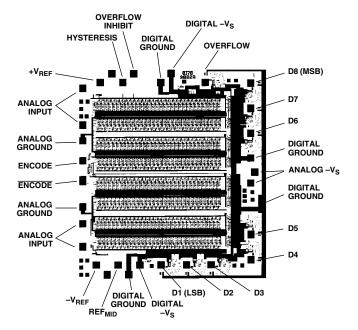


Figure 4. Die Layout and Mechanical Information

Die Dimensions	$\dots \dots 106 \times 114 \times 15 \ (\pm 2)$ mils
Pad Dimensions	$\ldots \ldots 4 \times 4$ mils
Metalization	Gold
Backing	None
Substrate Potential	V _s
Passivation	Nitride
Die Attach	Gold Eutectic (Ceramic)
	Epoxy (Plastic)
Bond Wire 1	1.3 mil Gold: Gold Ball Bonding

APPLICATION INFORMATION

The AD9002 is compatible with all standard ECL logic families, including 10K and 10KH. 100K ECL's logic levels are temperature compensated, and are therefore compatible with the AD9002 (and most other ECL device families) only over a limited temperature range. To operate at the highest encode rates, the supporting logic around the AD9002 will need to be equally fast. Whichever of the ECL logic families is used, special care must be exercised to keep digital switching noise away from the analog circuits around the AD9002. The two most critical items are digital supply lines and digital ground return.

The input capacitance of the AD9002 is an exceptionally low 17 pF. This allows the use of a wide range of input amplifiers, both hybrid and monolithic. To take full advantage of the wide input bandwidth of the AD9002, a hybrid amplifier such as the AD9610 will be required. For those applications that do not require the full input bandwidth of the AD9002, more traditional monolithic amplifiers, such as the AD846, will work very well. Overall performance with any amplifier can be improved by inserting a 10 Ω resistor in series with the amplifier output.

The output data is buffered through the ECL compatible output latches. All data is delayed by one clock cycle, in addition to the latch propagation delay (t_{PD}), before becoming available at the outputs. Both the analog-to-digital conversion cycle and the data transfer to the output latches are triggered on the rising edge of the differential, ECL compactible ENCODE signal (see timing diagram). In applications where only a single-ended signal is available, the AD96685, a high speed, ECL voltage comparator, can be employed to generate the differential signals. All ECL signals (including the overflow bit) should be terminated properly to avoid ringing and reflection.

The AD9002 also incorporates a HYSTERESIS control pin which provides from 0 mV to 10 mV of additional hysteresis in the comparator input stages. Adjustments in the HYSTERESIS control voltage may help improve noise immunity and overall performance in harsh environments.

The OVERFLOW INHIBIT pin of the AD9002 determines how the converter handles overrange inputs (AIN \geq +V_{REF}). In the "enabled" state (floating at –5.2 V), the OVERFLOW output will be at logic HIGH and all other outputs will be at logic LOW for overrange inputs (return-to-zero operation). In the "inhibited" state (tied to ground), the OVERFLOW output will be at logic LOW, and all other outputs will be at logic HIGH for overrange inputs (nonreturn-to-zero operation).

The AD9002 provides outstanding error rate performance. This is due to tight control of comparator offset matching and a fault tolerant decoding stage. Additional improvements in error rate are possible through the addition of hysteresis (see HYSTERESIS control pin). This level of performance is extremely important in fault-sensitive applications such as digital radio (QAM).

Dramatic improvements in comparator design and construction give the AD9002 excellent dynamic characteristics, especially SNR (signal-to-noise ratio). The 160 MHz input bandwidth and low error rate performance give the AD9002 an SNR of 48 dB with a 1.23 MHz input. High SNR performance is particularly important in wide bandwidth applications, such as pulse signature analysis, commonly performed in advanced radar receivers.

LAYOUT SUGGESTIONS

Designs using the AD9002, like all high speed devices, must follow a few basic layout rules to insure optimum performance. Essentially, these guidelines are meant to avoid many of the problems associated with high speed designs. The first requirement is for a substantial ground plane around and under the AD9002. Separate ground plane areas for the digital and analog components may be useful, but these separate grounds should be connected together at the AD9002 to avoid the effects of "ground loop" currents.

The second area that requires an extra degree of attention involves the three reference inputs, $+V_{REF}$, REF_{MID} , and $-V_{REF}$. The $+V_{REF}$ input and the $-V_{REF}$ input should both be driven from a low impedance source (note that the $+V_{REF}$ input is typically tied to analog ground). A low drift amplifier should provide satisfactory results, even over an extended temperature range. Adjustments at the REF_{MID} input may be useful in improving the integral linearity by correcting any reference ladder skews. The application circuit shown below demonstrates a simple and effective means of driving the reference circuit.

The reference inputs should be adequately decoupled to ground through 0.1 μ F chip capacitors to limit the effects of system noise on conversion accuracy. The power supply pins must also be decoupled to ground to improve noise immunity; 0.1 μ F and 0.01 μ F chip capacitors are recommended.

The analog input signal is brought into the AD9002 through two separate input pins. It is very important that the two input pins be driven symmetrically with equal length electrical connections. Otherwise, aperture delay errors may degrade converter performance at high frequencies.

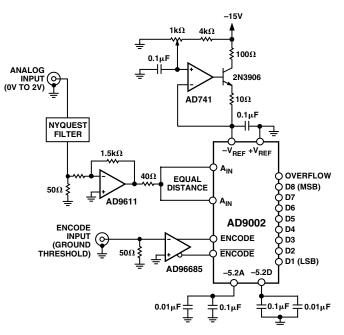


Figure 5. Typical Application

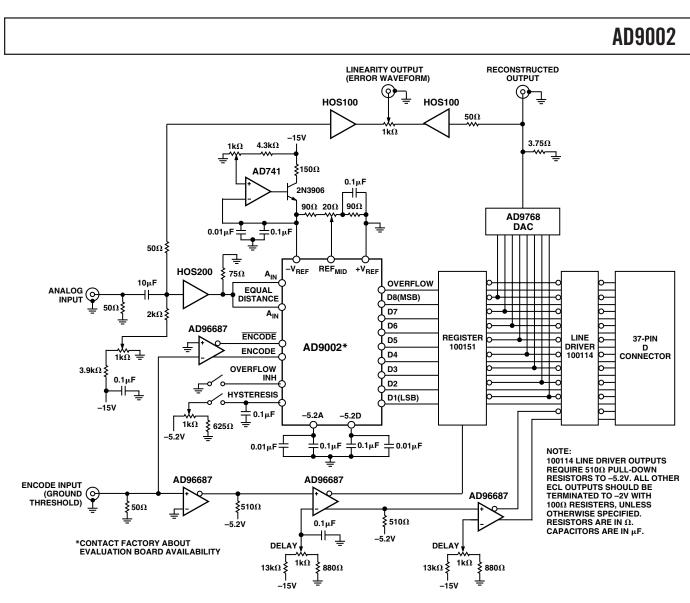


Figure 6. AD9002 Evaluation Circuit

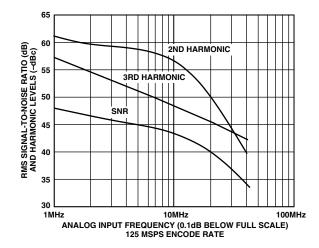
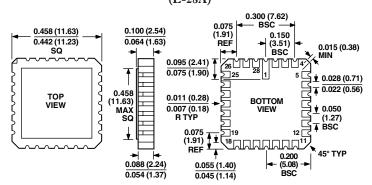


Figure 7. Dynamic Performance

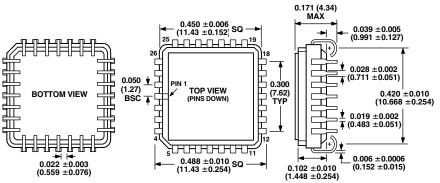
28-Lead Ceramic Side-Brazed DIP (D-28) 0.005 (0.13) MIN 0.100 (2.54) MAX 0.610 (15.49) 0.500 (12.70) PIN 1 0.620 (15.75) 0.590 (14.99) 1.490 (37.85) MAX 0.060 (1.52) 0.015 (0.38) 0.225 (5.72) ŧ MAX, 0.150 0.200 (5.08) 4 (3.81) ▼ MIN Ш 0.125 (3.18) 0.018 (0.46) ● ► 0.100 (2.54) BSC 0.026 (0.66) 0.070 (1.78) SEATING 0.008 (0.20) 0.014 (0.36) 0.030 (0.76)

OUTLINE DIMENSIONS Dimensions shown in inches and (mm).

28-Lead Ceramic Leadless Chip Carrier (E-28A)



28-Leaded JLCC (J-28)



Revision History

Location

Data Sheet changed from REV. E to REV. F.	
Edit to ABSOLUTE MAXIMUM RATINGS	 3

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